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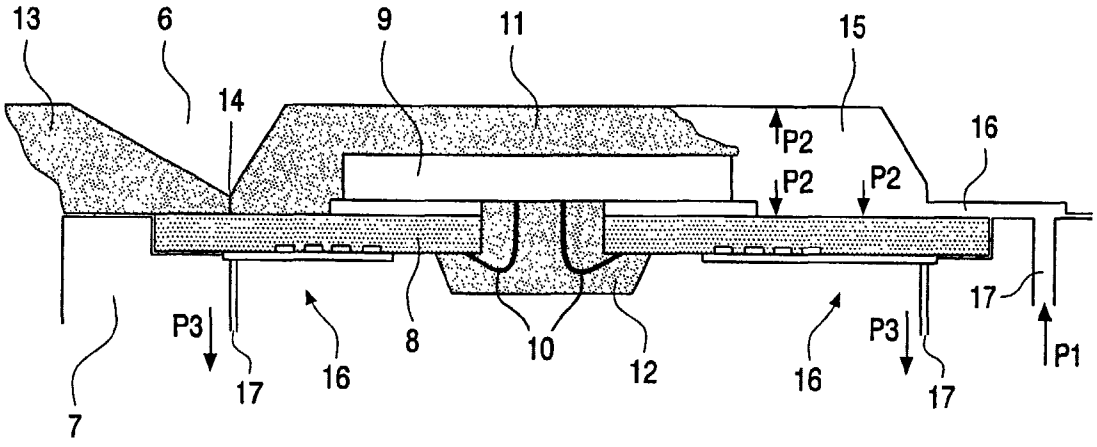
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(54) Title: METHOD AND DEVICE FOR ENCAPSULATING ELECTRONIC COMPONENTS WHILE EXERTING FLUID PRESSURE



(57) Abstract: The invention relates to a method for encapsulating electronic components, in particular semiconductors, by receiving a component for encapsulating between two mould halves displaceable relative to each other and feeding a liquid encapsulating material under overpressure by means of a transfer mechanism to at least one mould cavity arranged for this purpose, characterized in that during feeding of liquid encapsulating material to the mould cavity the part of the mould cavity not yet filled with encapsulating material is filled with a gas under overpressure. The invention also relates to a device for encapsulating electronic components.

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